

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V _{EBO}	6.0	V
Collector Current	Ic	200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	150	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\Theta JA}$	833	°C/W
Operating and Storage and Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge—Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge—Machine Model	ESD MM	400	V	С

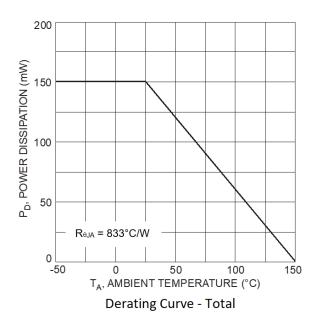
Notes:

^{5.} For the device mounted on minimum recommended pad layout FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristic and Derating Information





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

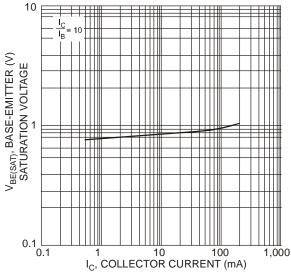
Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS				•		
Collector-Base Breakdown Voltage	BV _{CBO}	60	1	V	$I_C = 100\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 7)	BV_{CEO}	40	1	V	$I_C = 1.0 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV_{EBO}	6.0	_	V	$I_E = 100 \mu A, I_C = 0$	
Collector-Emitter Cut-Off Current	I _{CEV}		50	nA	$V_{CE} = 30V$, $V_{EB(OFF)} = 3.0V$	
Emitter-Base Cut-Off Current	I _{EBO}	_	50	nA	$V_{EB} = 6V$	
ON CHARACTERISTICS (Note 7)						
DC Current Gain	h _{FE}	40 70 100 60 30	 300 	_	$I_C = 100\mu A, V_{CE} = 1.0V$ $I_C = 1.0mA, V_{CE} = 1.0V$ $I_C = 10mA, V_{CE} = 1.0V$ $I_C = 50mA, V_{CE} = 1.0V$ $I_C = 100mA, V_{CE} = 1.0V$	
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	0.20 0.30	V	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA	
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.65 —	0.85 0.95	V	$I_C = 10mA$, $I_B = 1.0mA$ $I_C = 50mA$, $I_B = 5.0mA$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C _{OBO}	_	4.0	pF	$V_{CB} = 5.0V$, $f = 1.0MHz$, $I_E = 0$	
Input Capacitance	CIBO	_	8.0	pF	$V_{EB} = 0.5V$, $f = 1.0MHz$, $I_{C} = 0$	
Input Impedance	h _{ie}	1.0	10	kΩ		
Voltage Feedback Ratio	h _{re}	0.5	8.0	× 10 ⁻⁴	$V_{CE} = 10V, I_{C} = 1.0mA,$	
Small Signal Current Gain	h _{fe}	100	400	_	f = 1.0kHz	
Output Admittance	h _{oe}	1.0	40	μS		
Current Gain-Bandwidth Product	f _T	300		MHz	$V_{CE} = 20V, I_{C} = 10mA,$ f = 100MHz	
Noise Figure	NF	-	5.0	dB	$V_{CE} = 5.0V$, $I_{C} = 100\mu A$, $R_{S} = 1.0k\Omega$, $f = 1.0kHz$	
SWITCHING CHARACTERISTICS						
Delay Time	t _d	_	35	ns	$V_{CC} = 3.0V, I_C = 10mA,$	
Rise Time	t _r	_	35	ns	$V_{BE(OFF)} = -0.5V, I_{B1} = 1.0mA$	
Storage Time	ts	_	200	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Fall Time	t _f	_	50	ns	$I_{B1} = -I_{B2} = 1.0 \text{mA}$	

Note:

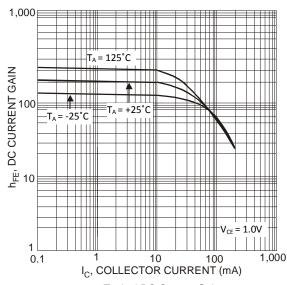
^{7.} Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



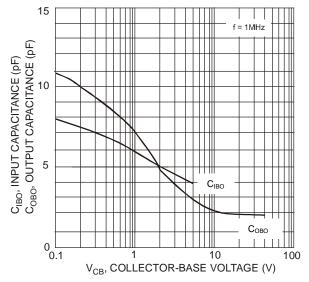
Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



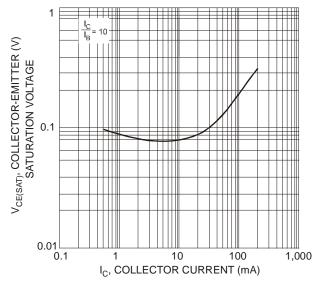
Typical Base-Emitter Saturation Voltage vs. Collector Current



Typical DC Current Gain vs. Collector Current



Input and Output Capacitance vs. Collector-Base Voltage

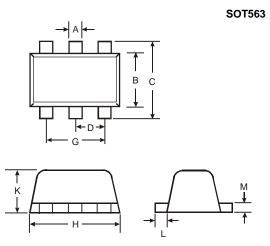


Typical Collector-Emitter Saturation Voltage vs. Collector Current



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

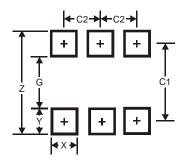


SOT563				
Dim	Min	Max	Тур	
Α	0.15	0.30	0.20	
В	1.10	1.25	1.20	
С	1.55	1.70	1.60	
D	-	-	0.50	
G	0.90	1.10	1.00	
Н	1.50	1.70	1.60	
K	0.55	0.60	0.60	
L	0.10	0.30	0.20	
М	0.10	0.18	0.11	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT563



Dimensions	SOT563
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5



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